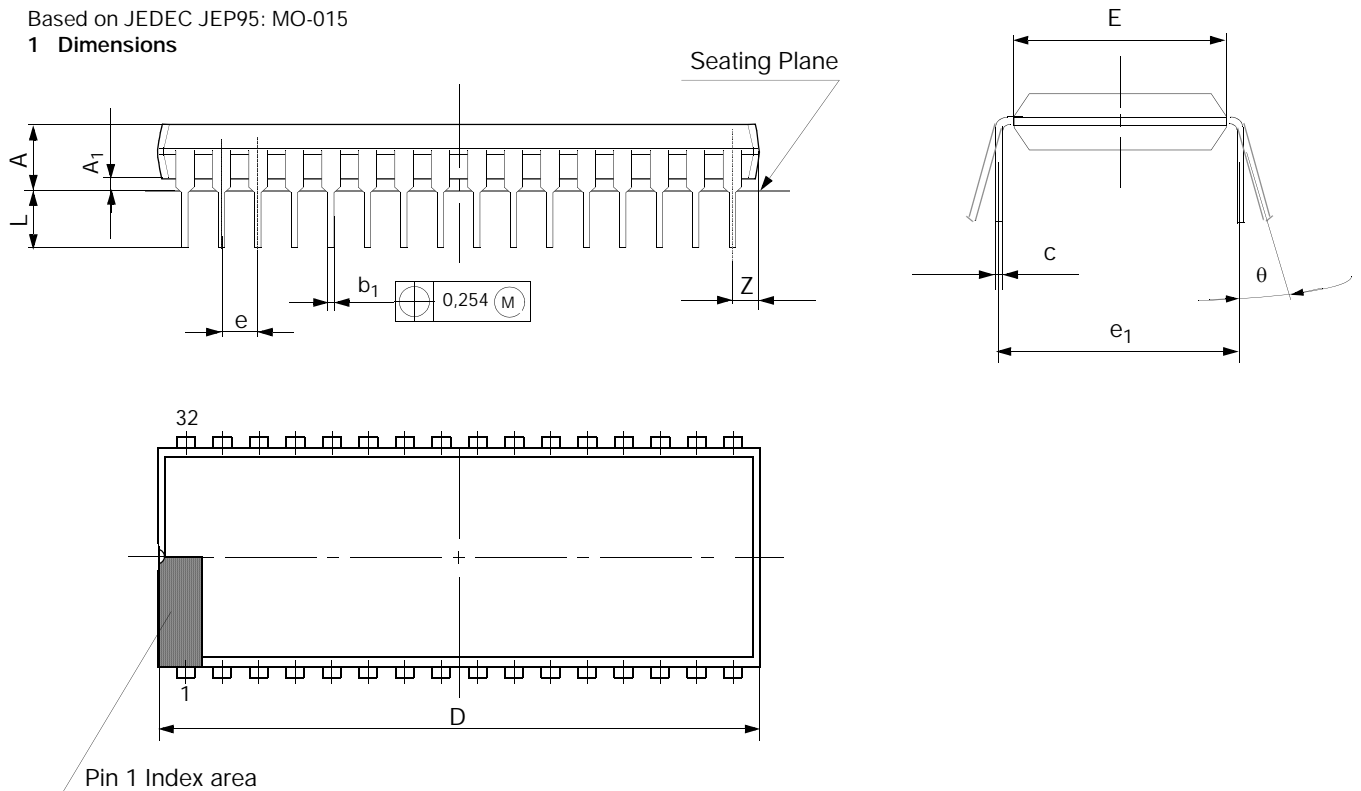
	Package PDIP32 (600 mil)	MDS 746
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Supersedes
Edition 03.97

Dimensions in millimetres

Based on JEDEC JEP95: MO-015

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	4,83
A_{1min}	0,38
b_{1min}^{**}	0,35
b_{1max}^{**}	0,59
c_{min}	0,20
c_{max}	0,36
e_{nom}	2,54
e_{1nom}	15,24
E_{min}^*	13,46
E_{max}^*	13,97
L_{min}	2,60
Z_{max}	2,03

Dimensions of Sub-Group C1	
A_{min}	4,32
A_{1max}	1,27
L_{max}	3,43
D_{min}^*	41,78
D_{max}^*	42,04
θ_{min}	0°
θ_{max}	15°

* without mold-flash

** The lead position tolerance requires slots with a minimum diameter of 0,7mm. The spacing between adjacent slots is 2,54mm.

- | | |
|--------------------------------|------------------------|
| 2 Weight | $\leq 4,7$ g |
| 3 Package Body Material | Low Stress Epoxy |
| 4 Lead Material | FeNi-Alloy or Cu-Alloy |
| 5 Lead Finish | solder plating |

Zentrum Mikroelektronik Dresden AG		
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